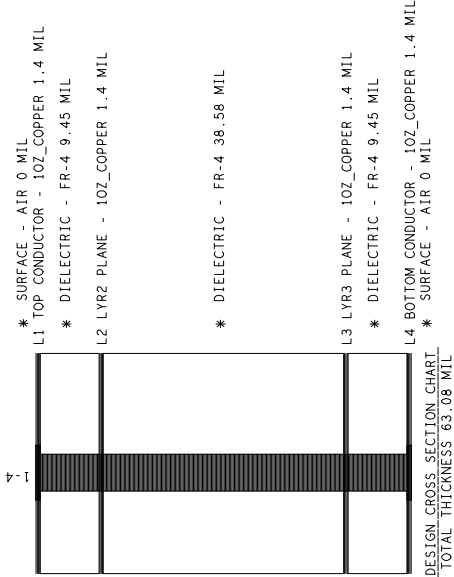


Finished Hole Tolerance - All units are in Inches -		
Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter	
0.008" - 0.013"	+0.002/-0.002"	
0.014" - 0.063"	+/-0.003"	
0.064" - 0.156"	+/-0.004"	
0.157" - 0.250"	+/-0.007"	
0.251" and up	+/-0.005"	
Non Plated Only		+0.003/-0.000"

DETAIL 'A'



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED_SIZE	PLATED	QTY
A	9.84	PLATED	307
B	35.43	PLATED	20
C	39.37	PLATED	3
D	44.0	PLATED	108
E	55.0	PLATED	5
F	63.0	PLATED	1

TOTAL HOLES : 444

REVISION DATE 21-Nov-24



APMS Group ITALY

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Drawn M. Rigo
Approved
date 12-June-24
date

Description
DRILLING AND PROFILING

Symbol
EVLSPIN9P1-3PH
Group

TOLERANCE UNLESS NOTED		ISO	SCALE:	REV.
UNIT=MM			1 : 1	2.0
linear	0 <10 >10 >50 <50 <200 >200	ANG. LES.	Material	
midle	±0.1 ±0.2 ±0.3 ±0.5	±1°	Treatment and surface finishing	
accurate	±0.05 ±0.1 ±0.15 ±0.25 ±30°			

FABRICATION NOTE :

- 1:FABRICATE USING LATEST REVISION OF IPC-6012B CLASS 2 OR ABOVE
- 2:FABRICATE USING MASTER ARTWORK EVLSPIN9P1-3PH R2 FOR CIRCUIT PATTERN.
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED STM REPRESENTATIVE
- 3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4:MATERIAL: FR4 RgHS COMPLIANT MINIMUM 170 C
SEE "DETAIL 'A'" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 5:SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE PER IPC-SM-840 (LATEST LEVEL). CLASS H. COLOR: BLUE
- 6:FINISH: ENIG Au>0.05u 3u<Ni<5u
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10:DESIGNATED AREA OR INSPECTION AND TEST STAMP
- 11:ON PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE
(MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 12:VENDOR TO PROVIDE BOARD STACK-UP AND IMPEDANCE (IF REQUIRED) APPROVAL PRIOR TO BOARD FABRICATION,STACK UP AND IMPEDANCE (IF REQUIRED) TO INCLUDE COPPER PLATING ON OUTER LAYERS.FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
- 13:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 14:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 15:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND SHORTS. APPLY TEST STAMP IN REFERENCED AREA
- 16: THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796